

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103713	((heat) near (spreader sink))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 11:45
L2	359	((heat) near (spreader sink)) with (molding near compound)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 11:46
L3	71	((heat) near (spreader sink)) with (molding near compound) with (substrate wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 11:53
L4	2	((heat) near (spreader sink)) with (molding near compound) with (substrate wafer) with (cut\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 11:54
L5	2	((heat) near (spreader sink)) with (molding near compound) with (substrate wafer) with (align\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 12:00
L6	22	((heat) near (spreader sink)) with (encapsul\$3 compound) with (substrate wafer) with (align\$3 cut\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 12:05
L7	7	6 and @ad<="20020930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 12:05

## EAST Search History

L8	473	((heat) near (spreader sink)) with (encapsul\$3 compound) with (substrate wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 12:05
L9	261	8 and @ad<="20020930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/20 12:05